

MOS FIELD EFFECT TRANSISTOR μ PA2560

Dual N-CHANNEL MOSFET FOR SWITCHING

DESCRIPTION

The μ PA2560 is Dual N-channel MOSFETs designed for Back light inverters and power management applications of portable equipments. Dual N-channel MOSFETs are assembled in one package, to contribute minimize the equipments.

FEATURES

- 4.5 V drive available
- · Low on-state resistance

 $R_{DS(on)1}$ = 50 m Ω MAX. (V_{GS} = 10 V, I_D = 2 A) $R_{DS(on)2}$ = 83 m Ω MAX. (V_{GS} = 4.5 V, I_D = 2 A)

- Built-in gate protection diode
- Small and surface mount package (8-pin VSOF (2429))

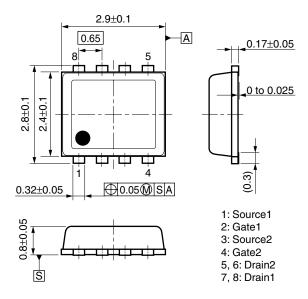
ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (V _{GS} = 0 V)	VDSS	30	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±20	V
Drain Current (DC)	ID(DC)	±4.5	Α
Drain Current (pulse) Note1	D(pulse)	±18	Α
Total Power Dissipation (1 unit, 5 s) Note2	P _{T1}	1.5	W
Total Power Dissipation (2 units, 5 s) Note2	P _{T2}	2.2	W
Channel Temperature	Tch	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on FR-4 board of 25.4 mm x 25.4 mm x 0.8 mm.

PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT (1/2)

Drain

ORDERING INFORMATION PART NUMBER LEAD PLATING PACKING PACKAGE μPA2560T1H-T1-AT Note Pure Sn 8 mm embossed taping 3000 p/reel 8-pin VSOF (2429)

Gate Protection Source Diode

Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

Marking: 2560

Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

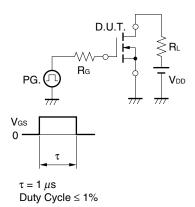


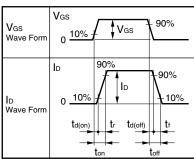
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ
Gate Leakage Current	Igss	V _{GS} = ±16 V, V _{DS} = 0 V			±10	μΑ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.0		2.5	V
Forward Transfer Admittance Note	yfs	V _{DS} = 10 V, I _D = 2 A	1			S
Drain to Source On-state Resistance Note	R _{DS(on)1}	V _{GS} = 10 V, I _D = 2 A		38	50	mΩ
	R _{DS(on)2}	V _{GS} = 4.5 V, I _D = 2 A		48	83	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V,		310		pF
Output Capacitance	Coss	V _{GS} = 0 V,		65		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		27		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15 V, I _D = 2 A,		6		ns
Rise Time	tr	V _{GS} = 10 V,		2.8		ns
Turn-off Delay Time	t _{d(off)}	R _G = 6 Ω		15		ns
Fall Time	tf			2.4		ns
Total Gate Charge	Q _G	V _{DD} = 24 V, V _{GS} = 10 V,		6.6		nC
		I _D = 4.5 A		0.0		IIC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 4.5 A, V _{GS} = 0 V		0.9		V

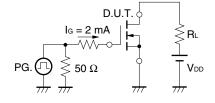
Note Pulsed

TEST CIRCUIT 1 SWITCHING TIME



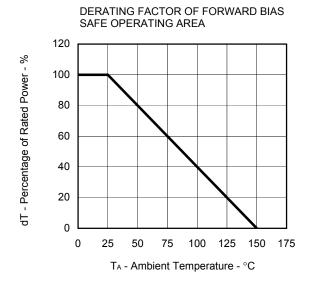


TEST CIRCUIT 2 GATE CHARGE

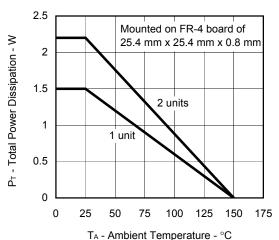




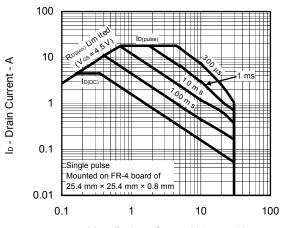
TYPICAL CHARACTERISTICS (TA = 25°C)



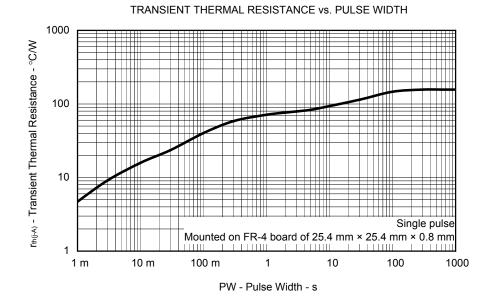
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA



V_{DS} - Drain to Source Voltage - V

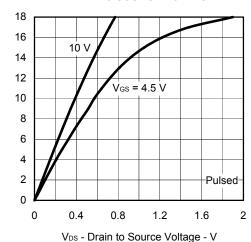


3

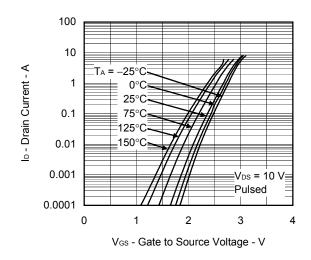


lo - Drain Current - A

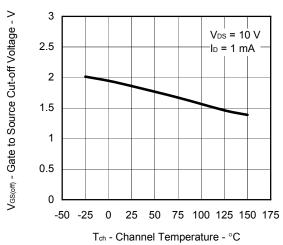
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



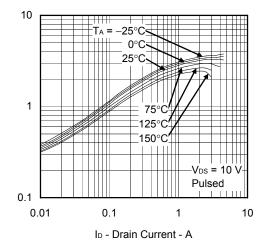
FORWARD TRANSFER CHARACTERISTICS



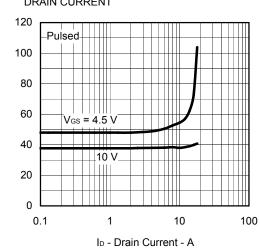
GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



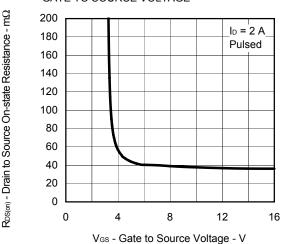
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



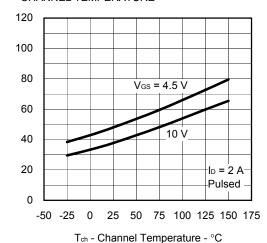
 $\mathsf{R}_{\mathsf{DS}(m)}$ - Drain to Source On-state Resistance - m Ω

| yfs | - Forward Transfer Admittance -



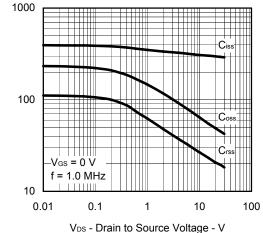
 $\mathsf{Ros}_{(m)}$ - Drain to Source On-state Resistance - $m\Omega$

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



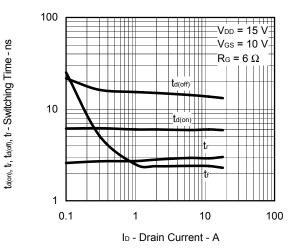
Ciss, Coss, Crss - Capacitance - pF

Vps - Drain to Source Voltage - V

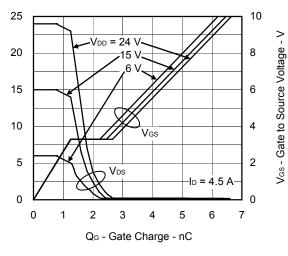


CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

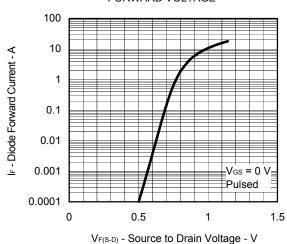
SWITCHING CHARACTERISTICS



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE





- The information in this document is current as of September, 2009. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual property rights of
 third parties by or arising from the use of NEC Electronics products listed in this document or any other liability arising from the
 use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual
 property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of a customer's equipment shall be done under the full responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree
 and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property
 or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient
 safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and "Specific". The "Specific" quality grade applies only to NEC Electronics products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.
- "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.
- "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
- "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

- (Note 1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majorityowned subsidiaries.
- (Note 2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

(M8E0909)